

CMOS Ripple-Carry Binary Counter/Dividers

High-Voltage Types (20-Volt Rating)

- CD4020B 14 Stage CD4024B - 7 Stage
- CD4040B 12 Stage

CD4020B, CD4024B, and CD4040B are ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of a counter advances one count on the negative transition of each input pulse; a high level on the RESET line resets the counter to its all zeros state. Schmitt trigger action on the input-pulse line permits unlimited rise and fall times. All inputs and outputs are buffered.

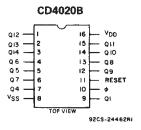
The CD4020B and CD4040B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line packages (E plastic suffix), 16-lead packages (NSR suffix), and small-outline 16-lead thin shrink small-outline packages (PW and PWR suffixes). The CD4040B type also is supplied in 16-lead small-outline packages (M and M96 suffixes).

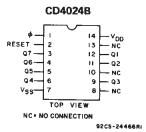
The CD4024B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

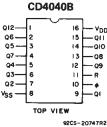
MAXIMUM RATINGS, Absolute-Maximum Values:

	DC SUPPLY-VOLTAGE RANGE, (V _{DD})
-0.5V to +20V	Voltages referenced to V _{SS} Terminal)
0.5V to V _{DD} +0.5V	INPUT VOLTAGE RANGE, ALL INPUTS
±10mA	DC INPUT CURRENT, ANY ONE INPUT
	POWER DISSIPATION PER PACKAGE (PD):
	For T _A = -55°C to +100°C
Derate Linearity at 12mW/°C to 200mW	For $T_A = +100^{\circ}C$ to $+125^{\circ}C$
	DEVICE DISSIPATION PER OUTPUT TRANSISTO
All Package Types) 100mW	FOR T _A = FULL PACKAGE-TEMPERATURE RA
55°C to +125°C	OPERATING-TEMPERATURE RANGE (TA)
	STORAGE TEMPERATURE RANGE (Tsto)
	LEAD TEMPERATURE (DURING SOLDERING):
e for 10s max	At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from the temperature of tempera

TERMINAL ASSIGNMENTS







Features:

- Medium-speed operation
- Fully static operation
- Buffered inputs and outputs
- 100% tested for guiescent current at 20 V
- Standardized, symmetrical output characteristics
- Fully static operation
- Common reset

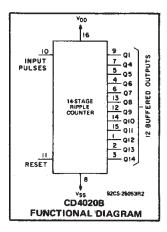
ture range):

- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-tempera-

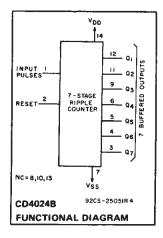
Meets all requirements of JEDEC Tentative Standard No. 138, "Standard Specifications for Description of 'B' Series CMOS Devices"

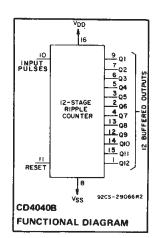
Applications:

- Control counters Frequency dividers Timers
 - Time-delay circuits



CD4020B, CD4024B, CD4040B Types

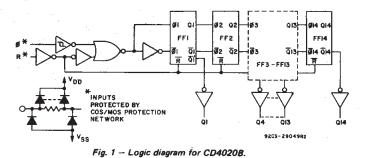


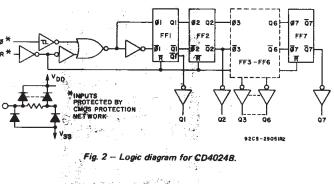


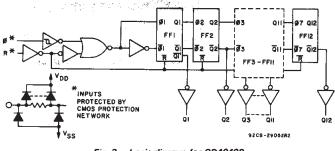
CD4020B, CD4024B, CD4040B Types

RECOMMENDED OPERATING CONDITIONS at T_A = 25^{\circ}C, Unless Otherwise Specified For maximum reliability, nominal operating conditions should be selected so that operation is always within the following range:

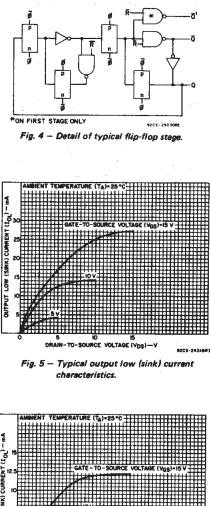
CHARACTERISTIC					
Supply Voltage Range (at T _A = Ful Temperature Range)	I Package-	VDD	3	18	V
Input-Pulse Frequency,	f _¢	5 10 15		3.5 8 12	MHz
Input-Pulse Width,	tw	5 10 15	140 60 40		ns
Input-Pulse Rise or Fall Time,	^t rø, ^t fø	5 10 15	Unlim	nited	μs
Reset Pulse Width,	tw	5 10 15	200 80 60	_	ns
Reset Removal Time,	tREM	5 10 15	350 150 100	-	ns





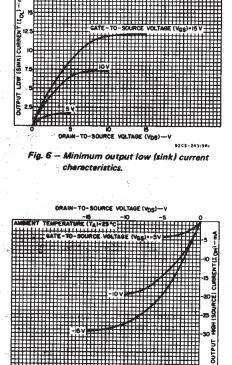






3

COMMERCIAL CMOS HIGH VOLTAGE ICs

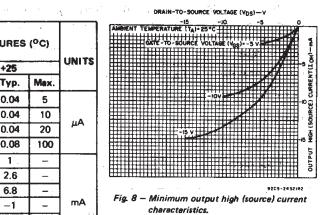


92CS-2432083 Fig. 7 — Typical output high (source) current characteristics,

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTER-	CONE	DITION	15	LIM	LIMITS AT INDICATED TEMPERATURES (°C)						
ISTIC	Vo	VIN	VDD					+25			UNITS
	(V)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent Device	_	0,5	5	5	5	150	150	÷	0.04	5	
Current,		0,10	10	10	10	300	300	-	0.04	10	
IOD Max.	-	0,15	15	20	20	600	600	-	0.04	20	μΑ
		0,20	20	100	100	3000	3000		0.08	100	
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1.	-	
(Sink) Current	0.5	0,10	10	1.6	1,5	-1.1	0.9	1.3	2.6		
IOL Min.	1,5	0,15	15.	4.2	4	2.8	2.4	34	6.8	- ;	
Output High	4.6	0,5	. 5 -	-0.64	-0.61	-0.42	-0.36	-0.51	1	-	mA
(Source)	2.5	0,5	5	2	-1.8	-1.3	-1.15	-1.6	-3.2	-	1 1
Current, IOH Min.	9,5	0,10	10	-1.6	-1:5	-1.1	-0.9 [.]	-1.3	-2.6	-	1
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage:	_	0,5	5		0	.05			0.	0.05	
Low-Level, VOL Max.	_	0,10	10		0	,05		-	0	0.05	-
	-	0,15	15		0	.05		-	0	0.05	
Output Voltage:		0,5	5		4	.95	_	4.95	5	- 1	
High-Level, VOH Min.	-	0,10	10		9	.95		9.95	10		
AOH warn'	-	0,15	15	λ.	14	1.95		14.95	15	-	
Input Low	0.5, 4.5	-	5		1	.5		-	-	1.5	
Voltage, Vit. Max.	1, 9	-	10			3			—	3	
VIL Max.	1.5,13.5	-	15			4		-	—	4	v
Input High	0.5, 4.5	_	5		3	3.5		3.5	—	-	
Voltage,	1, 9		10			7		7	-	_	
VIH Min.	1.5,13.5	_ ·	15			1		11		-	
Input Current IIN Max.	-	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μА



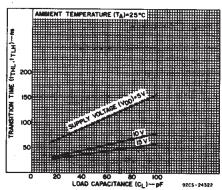
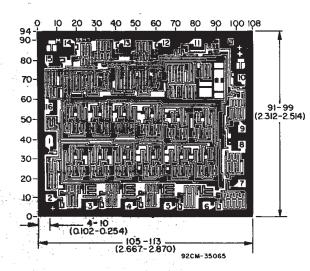
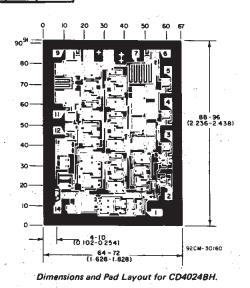


Fig. 9 - Typical transition time as a function of load capacitance.



Dimensions and Ped Layout for CD40208H. Dimensions and ped layout for CD40408H are identical.

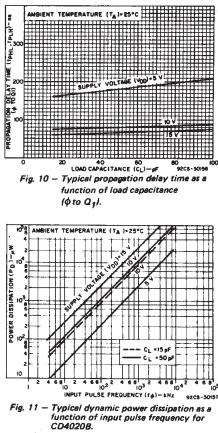
Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .



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DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^{\circ}$ C, Input t_r , $t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}, R_L = 200 \text{ k}\Omega$

				LIMITS				
CHARACTERISTIC	TEST CONDITIONS	V _{DD} (V)	Min.	Тур.	Max.	UNITS		
Input-Pulse Operation					· · · · ·			
Propagation Delay Time, ϕ to		5	-	180	360			
Q1 Out; tPHL, tPLH	1	10	-	80	160	ns		
		15	—	65	130			
0		5	_	100	330			
Q _n to Q _n + 1; ^t PHL ^{, t} PLH		10	—	40	80	ns		
		15		30	60	1		
Transition Time,		5	-	100	200			
^t THL ^{, t} TLH		10	-	50	100	ns		
		15	—	40	80			
Minimum Input-Pulse Width, t _W		5		70	140			
		10	-	30	60	ns		
		15	-	20	40			
		5						
Input-Pulse Rise or Fall		10	ι	μs				
Time, t _{rø} , t _{fø}		15	1					
Maximum Input-Pulse		5	3.5	7	-			
Frequency, f _d		10	8	16		MHz		
· · · · · · · ·		15	12	24	—]		
Input Capacitance, C ₁	Any Input		-	5	7.5	pF		
Reset Operation				·	·	L <u></u>		
Propagation Delay		5	_	140	280			
Time, tpHL	ļ [10	-	60	120	ns		
		15	-	50	100	1		
Minimum Reset Pulse		5		100	200			
Width, t _W		10		40	80	ns		
· · · · · · · · · · · · · · · · · · ·		15		30	60	1		
Reset Removal Time,		5	_	175	350]		
tREM		10		75	150	ns		
		15	-	50	100			



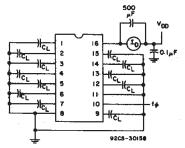
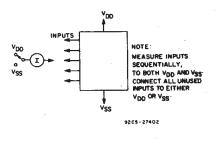
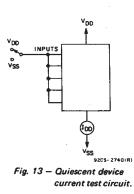
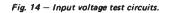


Fig. 12 - Dynamic power dissipation test circuit for CD4020B.







OUTPUTS

92C5-27441R1

TEST ANY COMBINATION OF INPUTS

Voo

∳ Vss

INPUTS

Fig. 15 - Input current test circuit.



4-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4020BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4020BE	Samples
CD4020BEE4	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4020BE	Samples
CD4020BF	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4020BF	Samples
CD4020BF3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4020BF3A	Samples
CD4020BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4020B	Samples
CD4020BNSRG4	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4020B	Samples
CD4020BPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM020B	Samples
CD4020BPWE4	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM020B	Samples
CD4020BPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM020B	Samples
CD4024BE	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4024BE	Samples
CD4024BEE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4024BE	Samples
CD4024BF	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4024BF	Samples
CD4024BF3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4024BF3A	Samples
CD4024BM	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024BM	Samples
CD4024BM96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024BM	Samples
CD4024BME4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024BM	Samples
CD4024BMG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024BM	Samples
CD4024BMT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024BM	Samples
CD4024BNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4024B	Samples



PACKAGE OPTION ADDENDUM

4-Feb-2021

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4024BPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM024B	Samples
CD4024BPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM024B	Samples
CD4040BE	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4040BE	Samples
CD4040BEE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4040BE	Samples
CD4040BF	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4040BF	Samples
CD4040BF3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4040BF3A	Samples
CD4040BM	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4040BM	Samples
CD4040BM96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4040BM	Samples
CD4040BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4040B	Samples
CD4040BPW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM040B	Samples
CD4040BPWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM040B	Samples
CD4040BPWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM040B	Samples
JM38510/05653BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05653BEA	Samples
JM38510/05655BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05655BCA	Samples
M38510/05653BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05653BEA	Samples
M38510/05655BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05655BCA	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



4-Feb-2021

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4020B, CD4020B-MIL, CD4024B, CD4024B-MIL, CD4040B, CD4040B-MIL :

- Catalog: CD4020B, CD4024B, CD4040B
- Military: CD4020B-MIL, CD4024B-MIL, CD4040B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4020BNSR	SO	NS	16	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
CD4020BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4024BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4024BMT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4024BNSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4024BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4040BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4040BNSR	SO	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
CD4040BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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PACKAGE MATERIALS INFORMATION

17-Dec-2020



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4020BNSR	SO	NS	16	2000	853.0	449.0	35.0
CD4020BPWR	TSSOP	PW	16	2000	853.0	449.0	35.0
CD4024BM96	SOIC	D	14	2500	853.0	449.0	35.0
CD4024BMT	SOIC	D	14	250	210.0	185.0	35.0
CD4024BNSR	SO	NS	14	2000	853.0	449.0	35.0
CD4024BPWR	TSSOP	PW	14	2000	853.0	449.0	35.0
CD4040BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4040BNSR	SO	NS	16	2000	853.0	449.0	35.0
CD4040BPWR	TSSOP	PW	16	2000	853.0	449.0	35.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW0016A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



PW0016A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0016A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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